

Patent Abstracts of Japan

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APPLICANT : NIPPON CARBIDE IND CO INC;

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TITLE : PRESSURE-SENSITIVE ADHESIVE COMPOSITION CURABLE BY ACTINIC RADIATION

ABSTRACT : PURPOSE: To provide the title composition which can form a pressure-sensitive adhesive layer excellent both in the pressure-sensitive adhesiveness and the initial adhesive power before irradiation with actinic radiation and in the rubber elasticity, the extensibility and the reduction in adhesive power after the irradiation and which is suitable particularly for the dicing of semiconductor wafer.

CONSTITUTION: The title composition contains a (co)polymer (A) capable of forming a pressure-sensitive adhesive layer, one or more compounds (B) having at least one vinyl ether group in the molecule, and one or more compounds (C) having at least two radical-polymerizable unsaturated groups in the molecule and other than the compounds B, wherein the total of the compounds B and C is 20-600 pts.wt. based on 100 pts.wt. compound A and the compound B accounts for 5-50wt.% of the total of the compounds B and C.

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copolymer (A) ?